

IN THE CLAIMS

This listing of claims replaces are prior listings:

1. (Currently Amended) A semiconductor apparatus comprising:

a housing in which device mounting portions are respectively formed on both one surface side and ~~the other~~another surface side thereof;

a first device mounted in the device mounting portion on ~~the one~~ surface side of ~~this~~the housing;

a second device mounted in the device mounting portion on the other surface side of the housing; and

a plurality of leads having wire bonding pad portions ~~for wire bonding~~, supported by the housing while exposing those pad portions to the device mounting portions, and connected ~~through via~~ wires to the first device or second device ~~in the device mounting portions~~, wherein,

~~said first and second exposed areas of said pad portions~~portion of at least one lead among the plurality of leads are exposed to the device mounting portions ~~in the position relation alternate with each other on the one surface side and the other surface side of the housing such that a pad portion area exposed on the one surface side is not coincident with a pad portion area exposed on the other surface side and is supported by the housing covering the unexposed area of the opposite side of the pad portion~~, and

~~this exposed portion serves as the connection portion of the wire bonding at least one of the exposed areas serves as a wire bonding pad.~~

2. (Currently Amended) The semiconductor apparatus as ~~ited~~claimed in claim 1, characterized in which;wherein:

said pad portion of ~~at said~~ least one lead is ~~formed~~ larger than the pad ~~portion~~portions of the other lead~~leads~~.

3. (Currently Amended) A semiconductor apparatus characterized by comprising:

a housing ~~in which~~with respective device mounting portions are ~~respectively formed on both one surface side and the other~~another surface side;

a first device mounted in the device mounting portion on said one surface side of ~~this the~~ housing;

a second device mounted in the device mounting portion on said the other surface side of the housing; and

a plurality of leads having wire bonding pad portions ~~for wire bonding~~, being supported by the housing while exposing those pad portions to the device mounting portions, and being connected ~~through via~~ wires to the first device or second device in the device mounting portions,

wherein,

first and second exposed areas of the pad portions of at least one lead among the plurality of leads are exposed to the device mounting portions in ~~the a~~ position relation alternate with each other such that the first and second exposed areas are not coincident with each other and is supported by the housing covering the unexposed area of the opposite side of the pad portion, on the one surface side and the other surface side of the housing, and

this exposed portion serves as the connection portion of the wire bonding the first exposed area is wire bonded to the first device and the second exposed area is wire bonded to the second device.

4. (Cancelled)

5. (New) The semiconductor apparatus as claimed in claim 3, wherein,
said pad portion of said least one lead is larger in than the pad portions of the other leads.